

Title (en)

Polishing method, semiconductor device fabrication method, and semiconductor fabrication apparatus

Title (de)

Poliervorgang, Halbleitereinrichtung, Herstellungsverfahren und Halbleiterherstellungsgerät

Title (fr)

Méthode de polissage, procédé de fabrication d'un composant semi-conducteur, et appareil de fabrication de semi-conducteur

Publication

**EP 0777266 A1 19970604 (EN)**

Application

**EP 96118198 A 19961113**

Priority

- JP 31705495 A 19951113
- JP 11057696 A 19960408

Abstract (en)

Chemical mechanical polisher is disclosed. A polishing slurry stored in a polishing slurry tank (41), used in this polishing contains a solvent and polishing particles dispersed in the solvent. The polishing particles are selected from silicon nitride, silicon carbide, and graphite. The material (6, 12, 16) to be polished is polished by using this polishing slurry. <IMAGE>

IPC 1-7

**H01L 21/306**; **H01L 21/3105**; **B24B 37/04**

IPC 8 full level

**B24B 37/00** (2012.01); **C09G 1/02** (2006.01); **H01L 21/304** (2006.01); **H01L 21/3105** (2006.01); **H01L 21/32** (2006.01)

CPC (source: EP KR US)

**B24B 37/04** (2013.01 - EP US); **C09G 1/02** (2013.01 - EP US); **H01L 21/304** (2013.01 - KR); **H01L 21/31053** (2013.01 - EP US); **H01L 21/32** (2013.01 - EP US); **Y10S 438/97** (2013.01 - EP US)

Citation (search report)

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**EP 96118198 A 19961113**; CN 96114541 A 19961112; DE 69619207 T 19961113; JP 11057696 A 19960408; KR 19960052266 A 19961106; TW 85112035 A 19961002; US 74751896 A 19961112